

TUTORIALS

Tony Oates, CHAIR

international reliability physics symposium

THE ADAM'S MARK HOTEL
DENVER, COLORADO
APRIL 7-10, 1997

TABLE OF CONTENTS

Topic 1.	CHIP RELIABILITY <i>Badih El-Kareh and William R. Tonti, IBM Microelectronics,</i>	1
Topic 2.	INTERCONNECT RELIABILITY OF BALL GRID ARRAY AND DIRECT CHIP ATTACH <i>Andrew Mawer, Interconnect Reliability and Analysis Group, Motorola Semiconductor Products Sector</i>	2
Topic 3.	COPPER METALLIZATION FOR SUB-MICRON TECHNOLOGY <i>Hazara S. Rathore and Du Nguyen, Semiconductor Research and Development Center, IBM</i>	3
Topic 4.	PLASMA CHARGING DAMAGE <i>Kin P. Cheung, Bell Labs / Lucent Technologies</i>	4
Topic 5.	WAFER LEVEL RELIABILITY: PUSHING THE ENVELOPE <i>Donald G. Pierce and Eric S. Snyder, Sandia Technologies, Inc.,</i>	5
Topic 6.	STANDARDS AND APPLICATIONS OF THERMAL TEST METHODS FOR SEMICONDUCTOR DEVICES <i>Tom Tarter, Advanced Micro Devices, and Bernie Siegal, Thermal Engineering Associates</i>	6
Topic 7.	OXIDE RELIABILITY <i>Robin Degraeve, IMEC</i>	7
Topic 8.	ADVANCED FAILURE ANALYSIS TECHNIQUES FOR DEFECT LOCALIZATION <i>Daniel L. Barton and Edward I. Cole Jr., Sandia National Laboratories</i>	8
Topic 9.	HISTORY OF HOT ELECTRON RELATED DEGRADATION INMOSFET's AND THE HYDROGEN/DEUTERIUM ISOTOPE EFFECT <i>Isik C. Kizilyalli, Bell Laboratories / Lucent Technologies, Jeff D. Bude, Bell Laboratories / Lucent Technologies, and Karl Hess, Beckman Institute</i>	9